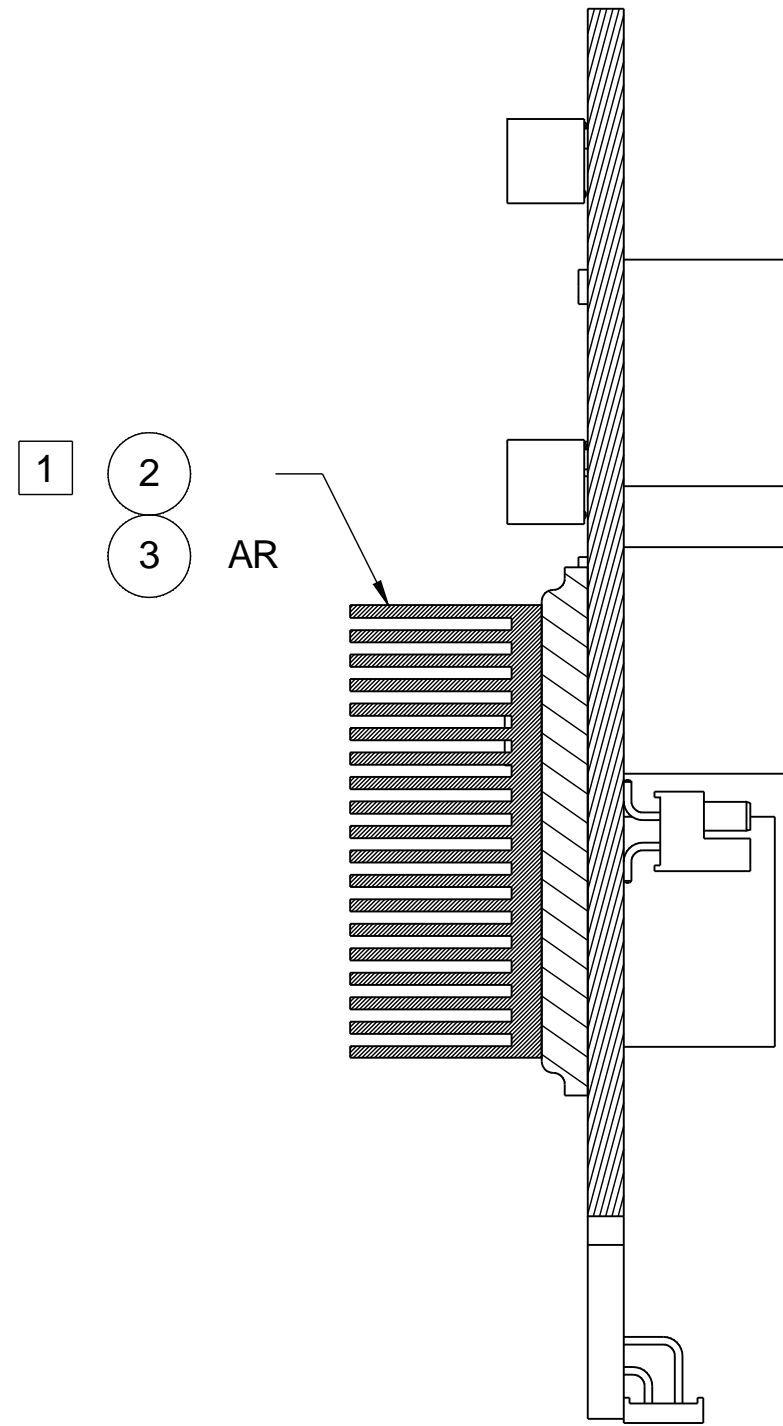
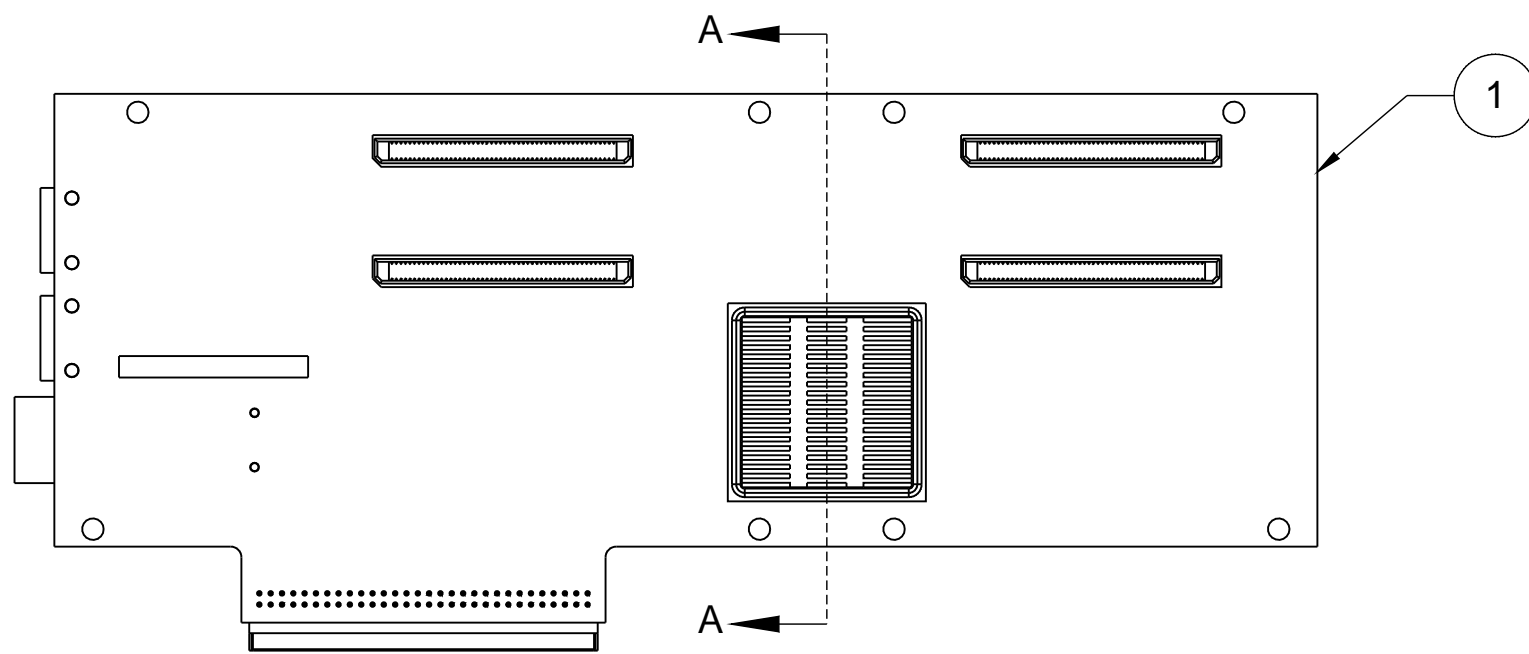
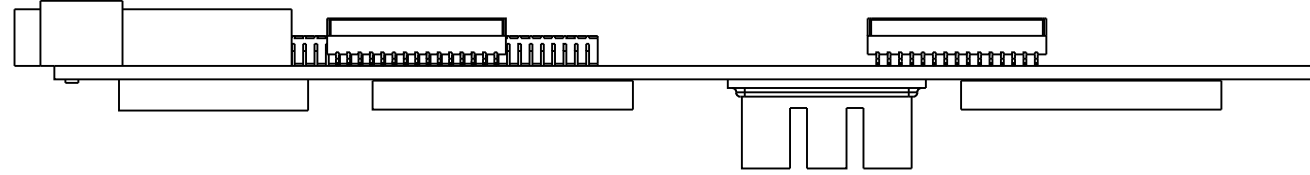
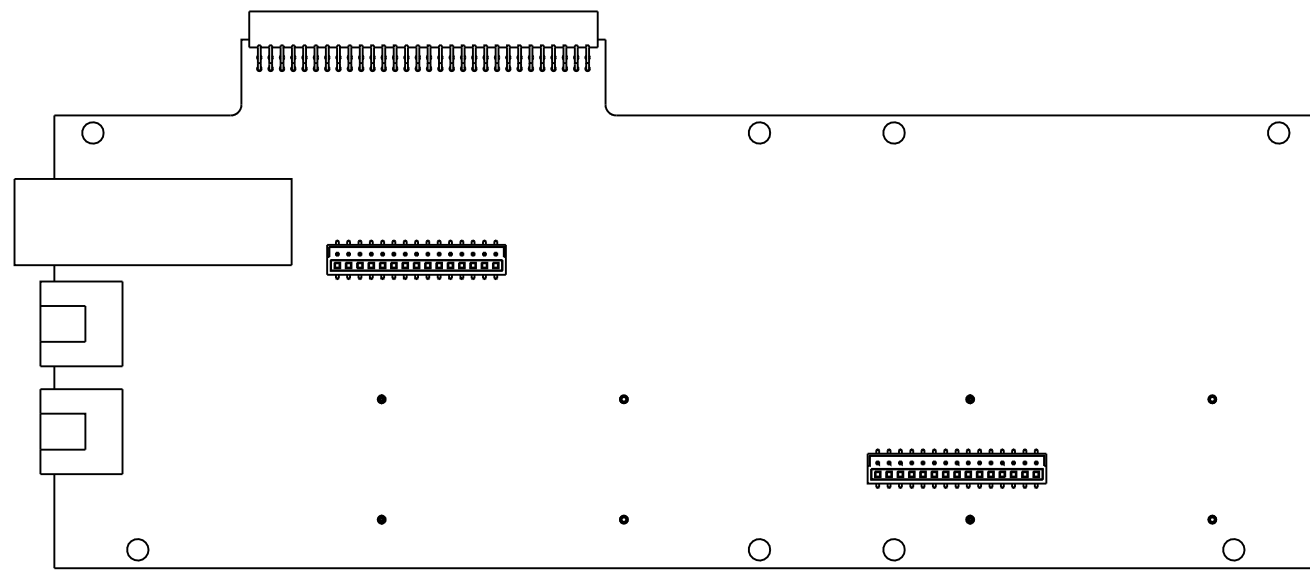


NOTES:

- 1 CLEAN MATING SURFACES OF HEATSINK AND FPGA CHIP WITH ALCOHOL.  
 BOND HEATSINK, ITEM 2 TO FPGA CHIP ON LOCAL CONTROL BOARD USING ADHESIVE, ITEM 3.  
 CAREFULLY PUSH DOWNWARD ON HEATSINK TO SQUEEZE OUT EXCESS ADHESIVE BEFORE CURING.  
 ALLOW TO DRY (RECOMMENDED CURE TIME 48 HOURS AT 20% MINIMUM RELATIVE HUMIDITY).  
 TRIM EXCESS CURED ADHESIVE AROUND EDGES.

ZONE	REV	DESCRIPTION	BY	DATE	APV BY
	B	CHANGED FPGA HEATSINK	JD	3/17/2011	
	A	ITEM 6 WAS CRES	JD	1/19/2011	
	-	INITIAL RELEASE	JD	7/23/2010	
REVISIONS					



SECTION A-A  
SCALE 2 : 1

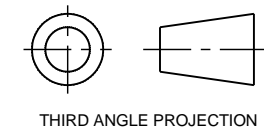
ITEM NO.	QUANTITY	MANUFACTURER	PART NO.	DESCRIPTION
1	1		TRNT-EL-04-0002	LOCAL CONTROL BOARD (LCB)
2	1	CTS THERMAL MANAGEMENT	APF30-30-13CB	HEATSINK
3	AR	DOW CORNING	SE 9184	THERMALLY CONDUCTIVE ADHESIVE

MATERIAL :

TOLERANCES UNLESS OTHERWISE NOTED

.XX ±.03  
.XXX ±.010

ANGULAR  
±.5°



NATIONAL OPTICAL ASTRONOMY OBSERVATORIES  
OPERATED BY THE  
ASSOCIATION OF UNIVERSITIES FOR RESEARCH IN ASTRONOMY  
UNDER COOPERATIVE AGREEMENT WITH  
NATIONAL SCIENCE FOUNDATION

DO NOT SCALE DRAWING

NEXT ASSEMBLY

TRNT-EL-02-0002

NAME

LCB ASSEMBLY

USED ON

**TORRENT**

DWG SIZE

**C**

REV

**B**

SCALE: 3:4

DWG PRODUCED USING  
SOLIDWORKS  
2010

DESIGNED BY:

DeVRIES / RATH

CHECKED BY:

XXX

DRAWN BY:

DeVRIES

APPROVED BY:

XXX

DRAWING NUMBER

TRNT-EL-02-0012

RELEASE DATE:

SHEET: 1 OF 1

ITEM	WEIGHT (Lbs)	CALCULATED WEIGHT
-1		